

Amendments to the Specification:

Please amend the title as follows:

MICROELECTRONIC ASSEMBLIES, ~~— AND —~~ ELECTRONIC DEVICES
INCLUDING CONNECTION STRUCTURES WITH MULTIPLE ELONGATED
MEMBERS AND APPARATUSES FOR SUPPORTING MICROELECTRONIC
SUBSTRATES

Please amend the CROSS-REFERENCE TO RELATED APPLICATIONS
section on page 1 as follows:

This application is a divisional application of U.S. Patent Application No. 10/034,924, filed December 26, 2001, entitled "APPARATUS FOR SUPPORTING MICROELECTRONIC SUBSTRATES," now U.S. Patent No. _____, issued _____; and is related to U.S. Application No. 10/_____ [Attorney Docket No. ~~108298633US2~~] 775,736, filed February 10, 2004, entitled "METHODS FOR COUPLING A FLOWABLE CONDUCTIVE MATERIAL TO MICROELECTRONIC SUBSTRATES," which is a divisional application of U.S. Application No. 10/034,924; both of which are herein incorporated by reference in their entireties.

Please amend the paragraph beginning on line 28 of page 9 as follows:

In one embodiment, the bond sites 131 and ~~450~~ 151 can each have a diameter of about 330 microns, and each elongated member 133a,b and 153a,b (and in particular, the inactive elongated member 153b) can have a length L of at least 250 microns. The apertures 127a,b in the cover layer 126 can have a diameter of about 430 microns. Accordingly, each bond site 131, 151 can be completely exposed through the corresponding aperture 127a, 127b. A portion 128 of each elongated member 133a,b and 153a,b can also be exposed for a distance D_1 of about 50 microns, measured from the edge of the corresponding bond site 131, 151, respectively. The elongated member 153b can be covered by the cover layer 126 for a distance D_2 of about 200 microns, and the remaining elongated members can be covered for

distances greater than D_2 . In other embodiments, the foregoing dimensions can have other values.